1-10. (CANCELED)

11. (PREVIOUSLY PRESENTED) The thermal conductive material according to claim 19, wherein the thermal conductive material is plasticized at 60°C under a pressure equal to or above 6.0 g/cm^2.

12. (CANCELED)

13. (PREVIOUSLY PRESENTED) The thermal conductive material according to claim 19, wherein the thermal conductive material is in an elastomeric state at room temperature.

14. (PREVIOUSLY PRESENTED) The thermal conductive material according to claim 19, wherein the organic material is an olefin resin.

15. (CANCELED)

16. (PREVIOUSLY PRESENTED) The thermal conductive material according to claim 19, wherein the filler is at least one of ceramics, metallic powder, metallic magnetic body and carbon fiber.

17. (PREVIOUSLY PRESENTED) The thermal conductive material according to claim 19, wherein the filler is a material serving as an electromagnetic shield.

18. (CANCELED)

19. (CURRENTLY AMENDED) A thermal conductive material comprising:

an unvulcanized ethylene-propylene-diene terpolymer ~~EPDM~~ organic material; and

a filler having a higher thermal conductivity than the unvulcanized ~~EPDM~~ ethylene-propylene-diene terpolymer organic material,

wherein the thermal conductive material is plasticized at a temperature in the range of 30-65°C and the thermal conductive material changes form to flexibly correspond to a form of a surface of a member with which the thermal conductive material comes in contact; and

the unvulcanized ethylene-propylene-diene terpolymer organic material has a melting transition in the range of 30-70°C and a viscosity at 100°C is equal to or above 70,000cP, a weight ratio of the filler to the thermal conductive material is in the range of 30-90 weight %.